

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT										
NATURE OF CONVEYANCE:	ASSIGNMENT										
CONVEYING PARTY DATA											
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>PHILIPPE VASSEUR</td> <td>01/17/2014</td> </tr> <tr> <td>GRIGORE D HUMINIC</td> <td>01/17/2014</td> </tr> <tr> <td>HERMANN KARAGOEZOGLU</td> <td>01/17/2014</td> </tr> <tr> <td>RADU M. MARINESCU</td> <td>01/17/2014</td> </tr> </tbody> </table>		Name	Execution Date	PHILIPPE VASSEUR	01/17/2014	GRIGORE D HUMINIC	01/17/2014	HERMANN KARAGOEZOGLU	01/17/2014	RADU M. MARINESCU	01/17/2014
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<table border="1"> <tr> <td>Name:</td> <td>EXCELITAS TECHNOLOGIES SINGAPORE PTE. LTD.</td> </tr> <tr> <td>Street Address:</td> <td>1 FUSIONOPOLIS WALK, #11-02</td> </tr> <tr> <td>City:</td> <td>SOLARIS SOUTH TOWER</td> </tr> <tr> <td>State/Country:</td> <td>SINGAPORE</td> </tr> <tr> <td>Postal Code:</td> <td>138628</td> </tr> </table>		Name:	EXCELITAS TECHNOLOGIES SINGAPORE PTE. LTD.	Street Address:	1 FUSIONOPOLIS WALK, #11-02	City:	SOLARIS SOUTH TOWER	State/Country:	SINGAPORE	Postal Code:	138628
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CORRESPONDENCE DATA											
<p>Fax Number:</p> <p>Phone: 603-668-0300</p> <p>Email: ipadm@SHEEHAN.COM</p> <p><i>Correspondence will be sent via US Mail when the email attempt is unsuccessful.</i></p> <p>Correspondent Name: SHEEHAN PHINNEY BASS + GREEN, PA</p> <p>Address Line 1: 1000 ELM STREET</p> <p>Address Line 4: MANCHESTER, NEW HAMPSHIRE 03101</p>											
ATTORNEY DOCKET NUMBER:	41067-6199										
NAME OF SUBMITTER:	KAREN A. MORIN										
Signature:	/Karen A. Morin/										

Date:

01/21/2014

Total Attachments: 2

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ASSIGNMENT

Whereas we, Grigore D. Huminic of Baie D'Urfe, Canada, Philippe Vasseur of Lachine, Canada, Hermann Karagoezoglu of Wiesbaden, Germany and Radu M. Marinescu of Pointe-Claire, Canada have invented certain new and useful improvements in:

CMOS Integrated Method for Fabrication of Thermopile Pixel on Semiconductor Substrate with Buried Insulation Regions

(hereinafter referred to as "Invention") for which we are making application for Letters Patent in the United States of America;

And, whereas we desire to assign a 100% undivided interest in said Invention, said application disclosing the Invention and any Letters Patent which may be granted therefore to **Excelitas Technologies Singapore Pte. Ltd. a Singapore corporation, having its place of business at 1 Fusionopolis Walk #11-02 Solaris South Tower Singapore 138628** (hereinafter referred to as "Assignee"), and whereas Assignee is desirous of acquiring the entire right, title and interest in the same;

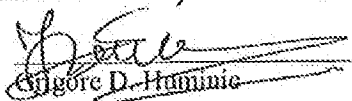
Now, this indenture witnesseth, that for the sum of one dollar (\$1.00), and other good and valuable consideration, the receipt whereof is hereby acknowledged;

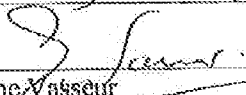
We hereby assign, sell and transfer a 100% undivided interest in said invention, said application, including any divisions, continuations, and continuations-in-part thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said Invention, and in and to any and all priority rights, Convention rights, and other benefits accruing or to accrue to us with respect to the filing of applications for patents or securing of patents in the United States and countries foreign thereto, unto said Assignee;

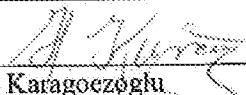
And we hereby authorize and request the Director of the United States Patent and Trademark Office to issue said United States Letters Patent to said Assignee, as assignee of the whole right, title and interest thereto;


And we further agree to execute all necessary and lawful future documents, including assignments in favor of Assignee, or its designees as Assignee or its Assignees may from time-to-time present to us in order to perfect title in said Invention, modifications, and improvements in said Invention, applications and Letters Patent of the United States and countries foreign thereto;

And we further agree to sign and properly execute such necessary and lawful papers for application for foreign patents, for filing divisions, continuations and continuations-in-part of said application for patent, and/or, for obtaining any reissue or reissues of any Letters Patent that may be granted for our aforesaid Invention, as the Assignee thereof shall hereafter require and prepare at its own expense.

Executed this 17th day of JANUARY, in the year 2014
at VAUSREUIL-DORION, QUEBEC, CANADA

Gildore D. Huminie

Executed this 17th day of JANUARY, in the year 2014
at VAUSREUIL-DORION, QUEBEC, CANADA

Philippe Vasseur

Executed this 17th day of JANUARY, in the year 2014
at Wiesbaden, Germany

Hermann Karagoezoglou

Executed this 17th day of JANUARY, in the year 2014
at VAUSREUIL-DORION, QUEBEC, CANADA

Radu M. Marin